

Inductors

PTH high current flat wire inductors

Series/Type: ERU33M

Date: September 2024

Rated inductance 1.4 ... 7.2 μ H

Rated current 50 ... 80 A

Construction

- Isolate alloy powder core
- Magnetically shielded
- Helical winding
- Self-leaded construction



Features

- High rated current
- Extremely low DC resistance
- Very low profile and smallest possible footprint
- RoHS-compatible
- Easily customized
- Qualified to AEC-Q200 REV E
- Suitable for lead-free reflow soldering as referenced in JEDEC-J-STD 020F

Applications

Energy storage chokes for

- DC-DC converters
- VRM modules
- POL converters
- Solar converters

Terminals

- Lead-free tinned

Assembly

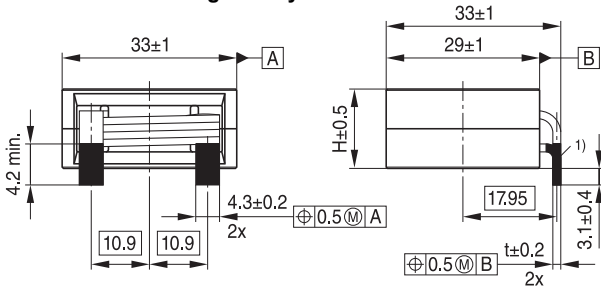
- Additional mechanical fixation required to fulfill the requirements for mechanical shock and vibration

Marking

- Manufacturer, ordering code, date code / production identification code

Delivery mode and packing unit

- Blister tray

Dimensional drawing and layout recommendation


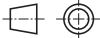
¹⁾ Tinned in this area

IND2202-H-E

Part tolerances to ISO 2768-cL / ISO 8015.

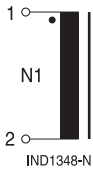
Size ISO 14405 (E)

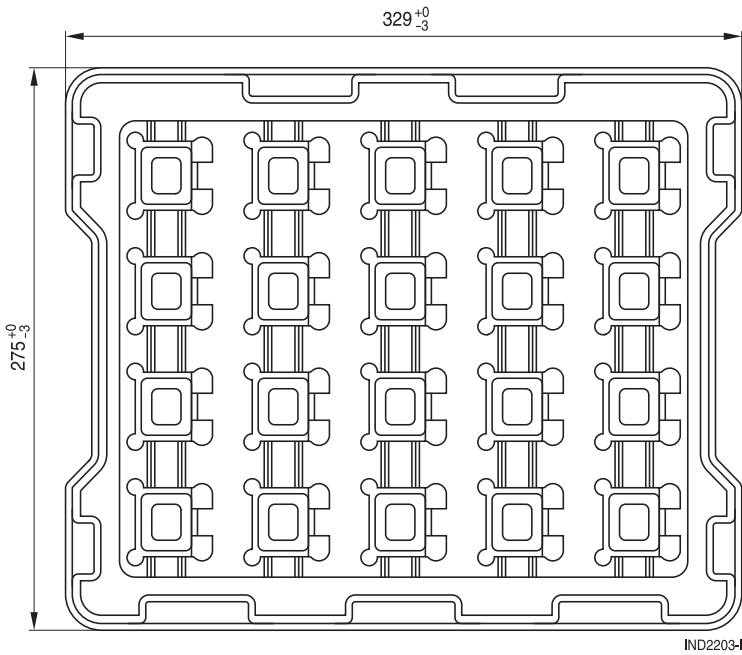
All dimensions in mm



IND1276-L-E

- Dimensions without tolerance are typical.
- () Dimensions for reference.
- Chamfer (w/o) on the core edges allowed.

Circuit diagram


Packing
Blister tray:


Component height nom. mm	Blister tray height nom. mm	Packing unit pcs per box
11.0	23.5	120
15.3	28.0	100

Technical data and measuring conditions

Specified at 25°C if not mentioned otherwise, all values without tolerance are typical values

Inductance L_R	Measured at 100 kHz, 0.1 V, +25 °C
Inductance tolerance	±15%
Saturation current I_{sat}	Current that will result in an approximately 20% drop in the inductance values at 100 °C
Temperature rise current I_{temp}	Current that will cause a ΔT 40 K self-heating at room temperature
DC resistance R_{DC}	Measured at +25 °C, tolerance ±10%, typical values
Self-resonant frequency	> 2 MHz
High voltage: N1 – core	200 V DC, 1 s
Solderability (test of wettability of the pins)	(245 ±5) °C, (3 ±0.3) s, wetting of soldering area ≥95% (based on IEC 60068-2-58, solder bath method)
Resistance to soldering heat	To JEDEC J-STD 020F (Tc: +245 °C on pin)
Operating temperature range	–40 °C ... +150 °C (component ¹⁾)
Storage conditions (packaged)	–25 °C ... +40 °C, ≤ 75% RH

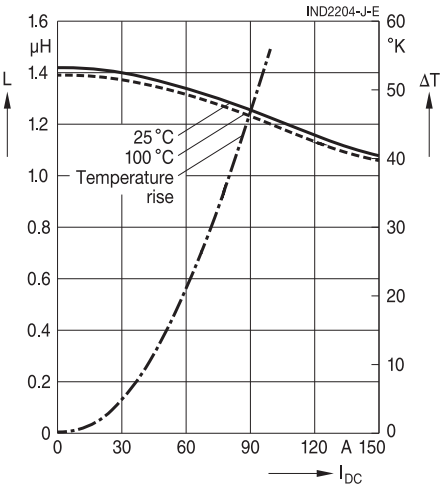
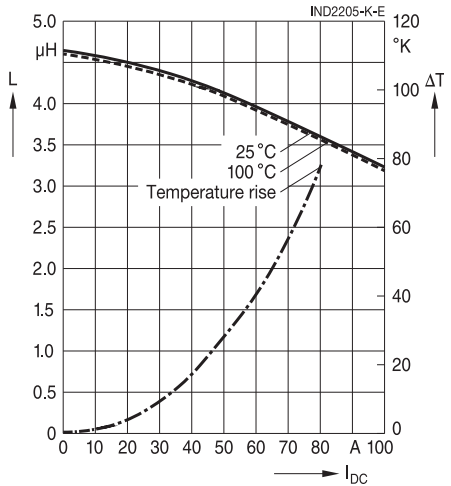
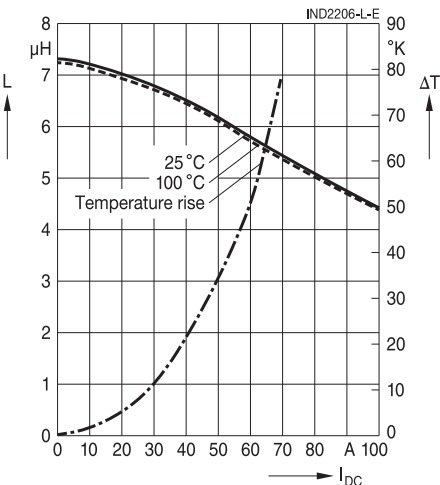
1) To keep the maximum limited component temperature the device must be connected to the cooling system

Characteristics and ordering codes

L_R	I_{sat} , 25°C	I_{sat} , 100°C	I_{temp}	R_{DC} (typ.)	Height h (nom.)	Pin thick- ness (nom.)	Approx. weight	Internal code	Ordering code
μH	A	A	A	mΩ	mm	mm	g		
1.4	120	120	80	0.46	11.0	1.50	58	B82579A1142A033	ERU33M-1R4L
4.6	75	75	58	0.85	15.3	1.50	76	B82579A1462A033	ERU33M-4R6L
7.2	55	55	50	1.20	15.3	1.25	77	B82579A1722A033	ERU33M-7R2L

Inductance L versus DC load current I_{DC}

The temperature rise ΔT is measured at an ambient temperature of +25 °C. A DC current is applied for 30 minutes and the temperature is measured on top of the inductor which is mounted on a printed circuit board. No forced air cooling is applied. The inductance vs current curves are generated by measuring the inductor at +25 °C and +100 °C.

ERU33M-1R4L

ERU33M-4R6L

ERU33M-7R2L


Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pins only. Temperatures specified in relation to reflow soldering can also refer to the pins or terminals for products with larger thermal mass, as in such cases, the temperature difference to the top of the component is too big (e.g., high proportion of core within the component).
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing or varnishing materials used attack or destroy the wire insulation, plastics, or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Cautions and warnings

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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Important notes

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